

1156901

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SMD socket, nominal current: 3 A, test voltage: 500 V AC, number of positions: 10, pitch: 2.54 mm, color: black, contact surface: Au, contact connection type: Socket, mounting: SMD soldering



Your advantages

- · Reliable mechanical and electrical connections thanks to the double-sided contact system
- · Designed for integration into the SMT soldering process
- · Clear and cost-optimized design
- · Suitable for a multitude of applications
- · Stacked, coplanar or orthogonal PCB connections enable maximum flexibility in the device

Commercial data

Item number	1156901
Packing unit	380 pc
Minimum order quantity	380 pc
Sales key	AA24
Product key	AAXABA
GTIN	4063151160265
Weight per piece (including packing)	1.45 g
Weight per piece (excluding packing)	1.4 g
Customs tariff number	85366930
Country of origin	CN



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Technical data

Notes

Notes on operation	The permissible voltage during operation depends on the application, taking into consideration the air clearances and
	creepage distances within the scope of insulation requirements in accordance with IEC 60664-1.

Product properties

Product type	SMD socket
Product family	FQ 2,54D/SH
Number of positions	10
Pitch	2.54 mm
Number of rows	2
Pin layout	Linear pad geometry
Electrical characteristic	shielded

Electrical properties

Properties

- P	
Nominal current I _N	3 A (at 20°C 80-pos.)
Contact resistance	20 mΩ
Test voltage	500 V AC IEC 60512-4-1:2003-05
Electrical characteristic	shielded

Dimensions

Dimensional drawing	P
Pitch	2.54 mm
Width [w]	13.1 mm
Height [h]	5 mm
Length [I]	15.74 mm
Installed height	5 mm
Application	
Contact cover	0.4 mm
Wipe length	1.3 mm
PCB design	
Pad geometry	1.04 x 1.32 mm

Material specifications



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Material data - contact

Note	WEEE/RoHS-compliant, free of whiskers according to IEC 60068-2-82/JEDEC JESD 201
Contact material	Cu alloy
Surface characteristics	Selective coating
Metal surface contact area (top layer)	Gold (Au)
Metal surface contact area (middle layer)	Nickel (Ni)
Metal surface soldering area (top layer)	Tin (Sn)

Material data - housing

3	
Color (Housing)	black (9005)
Insulating material	PA
Insulating material group	I
CTI according to IEC 60112	600
Flammability rating according to UL 94	V0

Connector

Connection 1

Insulating material	PA
CTI according to IEC 60112	600

Electrical tests

Thermal test | Test group C

Specification	IEC 60512-5-2:2002-02
Tested number of positions	80
Insulation resistance	
Specification	IEC 60512-3-1:2002-02
Insulation resistance, neighboring positions	> 1 GΩ
Air clearances and creepage distances	

Insulating material group	I
Minimum value for clearance and creepage distance	0.4 mm

Mechanical tests

Insertion and withdrawal forces

Result	Test passed
No. of cycles	100
Insertion strength per pos. approx.	2.9 N
Withdraw strength per pos. approx.	2.9 N

Visual inspection

Visual inspection	
Specification	IEC 60512-1-1:2002-02
Result	Test passed



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Specification	IEC 60512-1-2:2002-02
Result	Test passed

Environmental and real-life conditions

Vibration test

Specification	IEC 60068-2-6:2007-12
Frequency	10 - 55 - 10 Hz
Sweep speed	1 octave/min
Amplitude	1.52 mm
Acceleration	181 m/s²
Test duration per axis	2 h
Test directions	X-, Y- and Z-axis

Durability test

Specification	IEC 60512-9-1:2010-03 (following)
Contact resistance R ₁	20 mΩ
Contact resistance R ₂	30 mΩ
Insertion/withdrawal cycles	100
Insulation resistance, neighboring positions	> 1 GΩ

Ambient conditions

Ambient temperature (operation)	-40 °C 125 °C
Ambient temperature (storage/transport)	-40 °C 70 °C
Relative humidity (storage/transport)	30 % 70 %
Ambient temperature (assembly)	-5 °C 100 °C

Mounting

Pin layout Linear pad geometry	Mounting type	SMD soldering
- in a geomety	Pin layout	Linear pad geometry

Processing notes

Process	Reflow soldering
Moisture Sensitive Level	MSL 1
Classification temperature T _c	260 °C

Packaging specifications

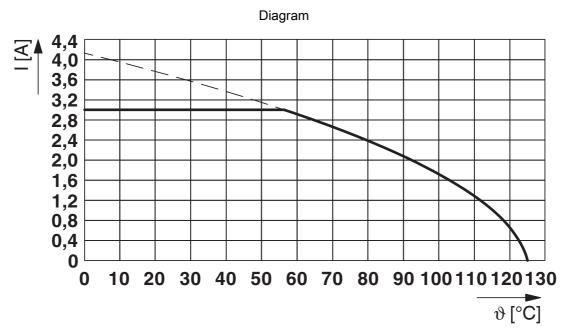
T () :	T	
Type of packaging	Tube magazine	



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Drawings



Type: FQ 2,54D/...-SH-O-BT with FQ 2,54D/...-PH-1-BT



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Approvals

To download certificates, visit the product detail page: https://www.phoenixcontact.com/us/products/1156901

e 911 us	cULus Recognize Approval ID: E118976	ed			
		Nominal voltage U _N	Nominal current I _N	Cross section AWG	Cross section mm ²
keine					
		30 V	3 A	-	-



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Classifications

UNSPSC 21.0

ECLASS

	ECLASS-13.0	27460201		
	ECLASS-13.0	27400201		
	ECLASS-15.0	27460201		
ETIM				
-				
	ETIM 9.0	EC002637		
LINCRO				
UNSPSC				

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Environmental product compliance

EU RoHS

20 1.01.0				
Fulfills EU RoHS substance requirements	Yes, No exemptions			
China RoHS				
Environment friendly use period (EFUP)	EFUP-E			
	No hazardous substances above the limits			
EU REACH SVHC				
REACH candidate substance (CAS No.)	No substance above 0.1 wt%			

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